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Customer No. 28289  
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No. : Not Yet Assigned  
Applicants : **Koichi NAGAMOTO et al.**  
Filed : Concurrently Herewith  
Title : **SURFACE-PROTECTING SHEET AND  
SEMICONDUCTOR WAFER LAPPING  
METHOD**  
International Application No. : PCT/JP2004/015131  
International Filing Date : 14 October 2004  
Priority Date(s) Claimed : 16 October 2003

**MAIL STOP PCT**  
Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

**PRELIMINARY AMENDMENT**

Sir:

Prior to initial examination, please amend the above-identified patent application as follows:

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 4 this paper.

**Remarks** begin on page 8 of this paper.